



ALLOY C19010M

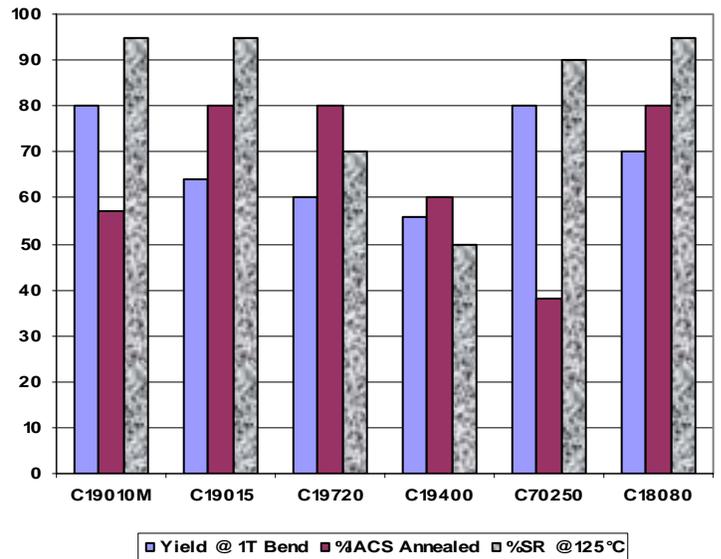
High Conductivity Copper-Nickel-Silicon

C19010M is an improved version and replacement to our popular Copper-Nickel Silicon Alloy C19010. The alloy demonstrates improved the strength, stress relaxation and coating performance compared to C19010. This meets the increasing needs of our customers to miniaturize, reduce gauge, push more current in terminal applications including hybrid and electric vehicles, electronics or to allow mixed power signal applications.

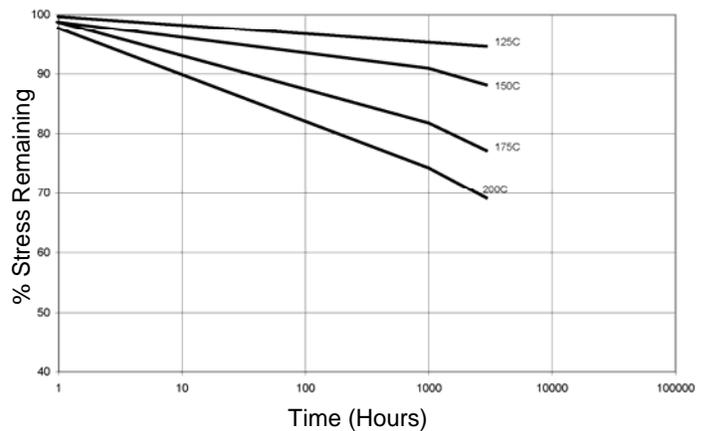
PMX C19010M performs well at service temperatures of 150-200°C. Additionally, to support the continuing demand for high temperature, low cost coatings PMX has engineered C19010M to perfectly match our high temperature, low insertion force tin-silver coatings – improved hot dip tinning performance, coating adhesion and high temperature behavior is achieved with PMX Tin-Silver C19010M.

PMX C19010M with Sn28M will enable your connector designs to use thinner materials, carry more current, operate more reliably and reduce insertion force. This system provides a viable alternative to advance barrier tins, nickel barrier reflow and a lower cost, lower insertion force option to pure silver. Sn28M can be mated with pure tin, pure silver, electroplates and reflow terminals without concern for mismatch. Additionally, Sn28M is compliant with today's lead-free solder system.

Enhanced performance and controlled total system costs – Available and supported through the PMX Alliance...That's the PMX Difference. Contact your PMX representative at 1-800-531-5268 or email us at sales@ipmx.com.



Stress Relaxation Performance of PMX C19010M



Temper	Tensile Strength (ksi)	Min Yield Strength (ksi)	90° GW/BW Bends
TM04	72-87	65	0/0
TM06	84-94	75	0.8/0.5
TM08	90-101	82	1.2/1

Details released herein are believed to be accurate at the time of issue and are considered for general information only. Use of this information is to be at the consumer's discretion.